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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-TQFP-64
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xc888-6ffi-5v-ac

1 Summary of Features

The XC886/888 has the following features:

- High-performance XC800 Core
  - compatible with standard 8051 processor
  - two clocks per machine cycle architecture (for memory access without wait state)
  - two data pointers
- On-chip memory
  - 12 Kbytes of Boot ROM
  - 256 bytes of RAM
  - 1.5 Kbytes of XRAM
  - 24/32 Kbytes of Flash; or
    24/32 Kbytes of ROM, with additional 4 Kbytes of Flash
    (includes memory protection strategy)
- I/O port supply at 3.3 V or 5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(more features on next page)

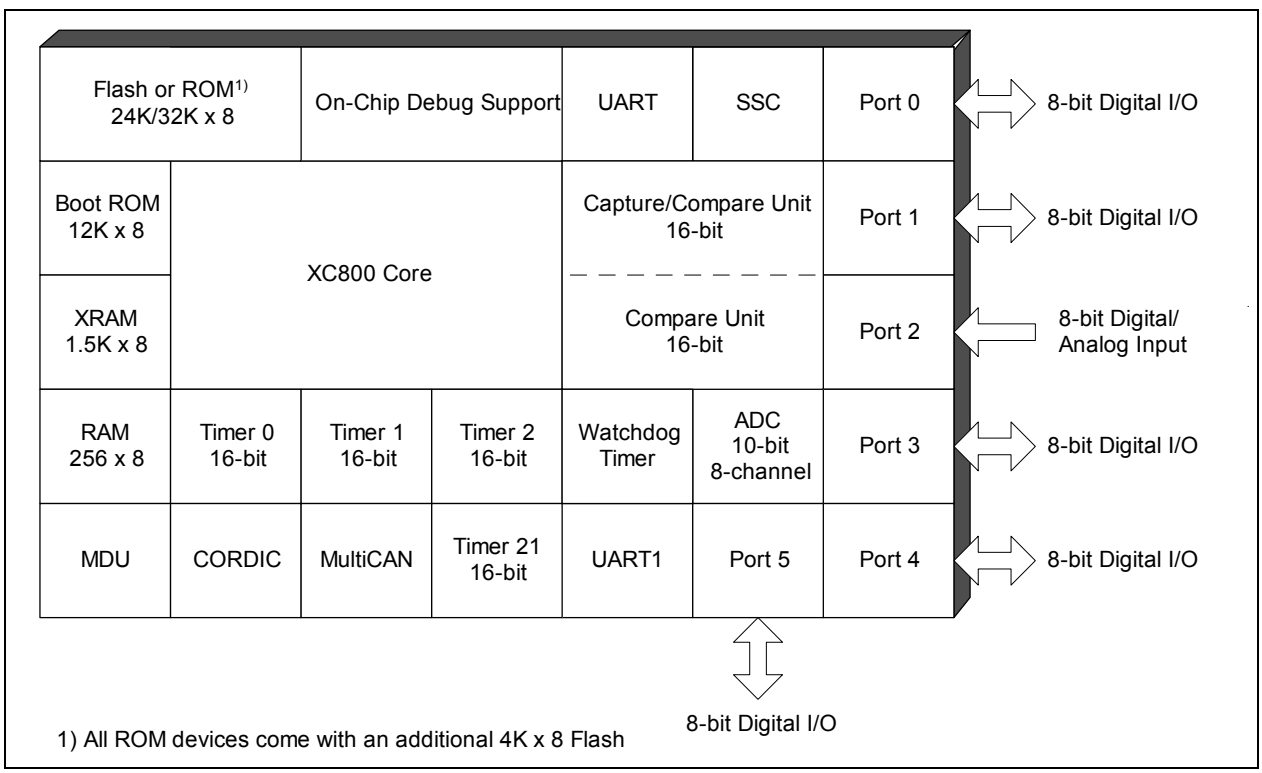


Figure 1 XC886/888 Functional Units

Table 2 Device Profile (cont'd)

Sales Type	Device Type	Program Memory (Kbytes)	Power Supply (V)	Temp-erature (°C)	Quality Profile
SAK-XC886*/888*-8FFA 3V3	Flash	32	3.3	-40 to 125	Automotive
SAK-XC886*/888*-6FFA 3V3	Flash	24	3.3	-40 to 125	Automotive
SAF-XC886*/888*-8FFA 3V3	Flash	32	3.3	-40 to 85	Automotive
SAF-XC886*/888*-6FFA 3V3	Flash	24	3.3	-40 to 85	Automotive
SAF-XC886*/888*-8FFI 3V3	Flash	32	3.3	-40 to 85	Industrial
SAF-XC886*/888*-6FFI 3V3	Flash	24	3.3	-40 to 85	Industrial

*Note: The asterisk (*) above denotes the device configuration letters from **Table 1**. Corresponding ROM derivatives will be available on request.*

Note: For variants with LIN BSL support, only LIN BSL is available regardless of the availability of the CAN module.

As this document refers to all the derivatives, some description may not apply to a specific product. For simplicity, all versions are referred to by the term XC886/888 throughout this document.

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- The package and the type of delivery

For the available ordering codes for the XC886/888, please refer to your responsible sales representative or your local distributor.

Note: The ordering codes for the Mask-ROM versions are defined for each product after verification of the respective ROM code.

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function	
P0.4	1/64		Hi-Z	MTSR_1	SSC Master Transmit Output/ Slave Receive Input
				CC62_1	Input/Output of Capture/Compare channel 2
				TXD1_0	UART1 Transmit Data Output/Clock Output
P0.5	2/1		Hi-Z	MRST_1	SSC Master Receive Input/Slave Transmit Output
				EXINT0_0	External Interrupt Input 0
				T2EX1_1	Timer 21 External Trigger Input
				RXD1_0	UART1 Receive Data Input
				COUT62_1	Output of Capture/Compare channel 2
P0.6	–/2		PU	GPIO	
P0.7	47/62		PU	CLKOUT_1	Clock Output

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P3		I/O		**Port 3** Port 3 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for CCU6, UART1, Timer 21 and MultiCAN.
P3.0	35/43		Hi-Z	CCPOS1_2 CCU6 Hall Input 1 CC60_0 Input/Output of Capture/Compare channel 0 RXDO1_1 UART1 Transmit Data Output
P3.1	36/44		Hi-Z	CCPOS0_2 CCU6 Hall Input 0 CC61_2 Input/Output of Capture/Compare channel 1 COUT60_0 Output of Capture/Compare channel 0 TXD1_1 UART1 Transmit Data Output/Clock Output
P3.2	37/49		Hi-Z	CCPOS2_2 CCU6 Hall Input 2 RXDC1_1 MultiCAN Node 1 Receiver Input RXD1_1 UART1 Receive Data Input CC61_0 Input/Output of Capture/Compare channel 1
P3.3	38/50		Hi-Z	COUT61_0 Output of Capture/Compare channel 1 TXDC1_1 MultiCAN Node 1 Transmitter Output
P3.4	39/51		Hi-Z	CC62_0 Input/Output of Capture/Compare channel 2 RXDC0_1 MultiCAN Node 0 Receiver Input T2EX1_0 Timer 21 External Trigger Input
P3.5	40/52		Hi-Z	COUT62_0 Output of Capture/Compare channel 2 EXF21_0 Timer 21 External Flag Output TXDC0_1 MultiCAN Node 0 Transmitter Output
P3.6	33/41		PD	$\overline{\text{CTRAP\_0}}$ CCU6 Trap Input

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function	
P5		I/O		**Port 5** Port 5 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for UART, UART1 and JTAG.	
P5.0	–/8		PU	EXINT1_1	External Interrupt Input 1
P5.1	–/9		PU	EXINT2_1	External Interrupt Input 2
P5.2	–/12		PU	RXD_2	UART Receive Data Input
P5.3	–/13		PU	TXD_2	UART Transmit Data Output/Clock Output
P5.4	–/14		PU	RXDO_2	UART Transmit Data Output
P5.5	–/15		PU	TDO_2 TXD1_2	JTAG Serial Data Output UART1 Transmit Data Output/ Clock Output
P5.6	–/19		PU	TCK_2 RXDO1_2	JTAG Clock Input UART1 Transmit Data Output
P5.7	–/20		PU	TDI_2 RXD1_2	JTAG Serial Data Input UART1 Receive Data Input

code or data. Therefore, even though the ROM device contains either a 24-Kbyte or 32-Kbyte ROM, the maximum size of code that can be placed in the ROM is the given size less four bytes.

3.2.1 Memory Protection Strategy

The XC886/888 memory protection strategy includes:

- Read-out protection: The user is able to protect the contents in the Flash (for Flash devices) and ROM (for ROM devices) memory from being read
  - Flash protection is enabled by programming a valid password (8-bit non-zero value) via BSL mode 6.
  - ROM protection is fixed with the ROM mask and is always enabled.
- Flash program and erase protection: This feature is available only for Flash devices.

3.2.1.1 Flash Memory Protection

As long as a valid password is available, all external access to the device, including the Flash, will be blocked.

For additional security, the Flash hardware protection can be enabled to implement a second layer of read-out protection, as well as to enable program and erase protection.

Flash hardware protection is available only for Flash devices and comes in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

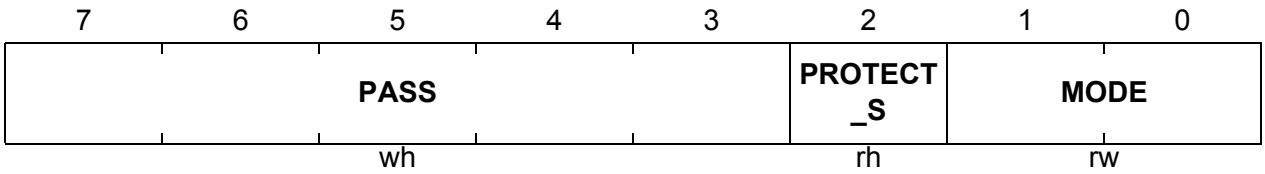
The selection of each protection mode and the restrictions imposed are summarized in **Table 4**.

Table 4 Flash Protection Modes

Flash Protection	Without hardware protection	With hardware protection	
Hardware Protection Mode	-	0	1
Activation	Program a valid password via BSL mode 6		
Selection	Bit 4 of password = 0	Bit 4 of password = 1 MSB of password = 0	Bit 4 of password = 1 MSB of password = 1
P-Flash contents can be read by	Read instructions in any program memory	Read instructions in the P-Flash	Read instructions in the P-Flash or D-Flash
External access to P-Flash	Not possible	Not possible	Not possible

3.2.3.1 Password Register

PASSWD
Password Register **Reset Value: 07_H**



Field	Bits	Type	Description
MODE	[1:0]	rw	**Bit Protection Scheme Control Bits** 00 Scheme disabled - direct access to the protected bits is allowed. 11 Scheme enabled - the bit field PASS has to be written with the passwords to open and close the access to protected bits. (default) Others:Scheme Enabled. These two bits cannot be written directly. To change the value between 11_B and 00_B, the bit field PASS must be written with 11000_B; only then, will the MODE[1:0] be registered.
PROTECT_S	2	rh	**Bit Protection Signal Status Bit** This bit shows the status of the protection. 0 Software is able to write to all protected bits. 1 Software is unable to write to any protected bits.
PASS	[7:3]	wh	**Password Bits** The Bit Protection Scheme only recognizes three patterns. 11000_B Enables writing of the bit field MODE. 10011_B Opens access to writing of all protected bits. 10101_B Closes access to writing of all protected bits

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CD_H	**ADC_LCBR Reset: $B7_H$** Limit Check Boundary Register	Bit Field	BOUND1				BOUND0			
		Type	rw				rw			
CE_H	**ADC_INPCR0 Reset: 00_H** Input Class 0 Register	Bit Field	STC							
		Type	rw							
CF_H	**ADC_ETRCR Reset: 00_H** External Trigger Control Register	Bit Field	SYNEN1	SYNEN0	ETRSEL1			ETRSEL0		
		Type	rw	rw	rw			rw		
RMAP = 0, PAGE 1										
CA_H	**ADC_CHCTR0 Reset: 00_H** Channel Control Register 0	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CB_H	**ADC_CHCTR1 Reset: 00_H** Channel Control Register 1	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CC_H	**ADC_CHCTR2 Reset: 00_H** Channel Control Register 2	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CD_H	**ADC_CHCTR3 Reset: 00_H** Channel Control Register 3	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CE_H	**ADC_CHCTR4 Reset: 00_H** Channel Control Register 4	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CF_H	**ADC_CHCTR5 Reset: 00_H** Channel Control Register 5	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
$D2_H$	**ADC_CHCTR6 Reset: 00_H** Channel Control Register 6	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
$D3_H$	**ADC_CHCTR7 Reset: 00_H** Channel Control Register 7	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
RMAP = 0, PAGE 2										
CA_H	**ADC_RESR0L Reset: 00_H** Result Register 0 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CB_H	**ADC_RESR0H Reset: 00_H** Result Register 0 High	Bit Field	RESULT							
		Type	rh							
CC_H	**ADC_RESR1L Reset: 00_H** Result Register 1 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CD_H	**ADC_RESR1H Reset: 00_H** Result Register 1 High	Bit Field	RESULT							
		Type	rh							
CE_H	**ADC_RESR2L Reset: 00_H** Result Register 2 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CF_H	**ADC_RESR2H Reset: 00_H** Result Register 2 High	Bit Field	RESULT							
		Type	rh							
$D2_H$	**ADC_RESR3L Reset: 00_H** Result Register 3 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$D3_H$	**ADC_RESR3H Reset: 00_H** Result Register 3 High	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 3										
CA_H	**ADC_RESRA0L Reset: 00_H** Result Register 0, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CB_H	**ADC_RESRA0H Reset: 00_H** Result Register 0, View A High	Bit Field	RESULT							
		Type	rh							
CC_H	**ADC_RESRA1L Reset: 00_H** Result Register 1, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CD_H	**ADC_RESRA1H Reset: 00_H** Result Register 1, View A High	Bit Field	RESULT							
		Type	rh							
CE_H	**ADC_RESRA2L Reset: 00_H** Result Register 2, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CF_H	**ADC_RESRA2H Reset: 00_H** Result Register 2, View A High	Bit Field	RESULT							
		Type	rh							
$D2_H$	**ADC_RESRA3L Reset: 00_H** Result Register 3, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
$D3_H$	**ADC_RESRA3H Reset: 00_H** Result Register 3, View A High	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 4										
CA_H	**ADC_RCR0 Reset: 00_H** Result Control Register 0	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CB_H	**ADC_RCR1 Reset: 00_H** Result Control Register 1	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CC_H	**ADC_RCR2 Reset: 00_H** Result Control Register 2	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CD_H	**ADC_RCR3 Reset: 00_H** Result Control Register 3	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CE_H	**ADC_VFCR Reset: 00_H** Valid Flag Clear Register	Bit Field	0				VFC3	VFC2	VFC1	VFC0
		Type	r				w	w	w	w
RMAP = 0, PAGE 5										
CA_H	**ADC_CHINFR Reset: 00_H** Channel Interrupt Flag Register	Bit Field	CHINF7	CHINF6	CHINF5	CHINF4	CHINF3	CHINF2	CHINF1	CHINF0
		Type	rh	rh	rh	rh	rh	rh	rh	rh
CB_H	**ADC_CHINCR Reset: 00_H** Channel Interrupt Clear Register	Bit Field	CHINC7	CHINC6	CHINC5	CHINC4	CHINC3	CHINC2	CHINC1	CHINC0
		Type	w	w	w	w	w	w	w	w

3.5 Parallel Ports

The XC886 has 34 port pins organized into five parallel ports, Port 0 (P0) to Port 4 (P4), while the XC888 has 48 port pins organized into six parallel ports, Port 0 (P0) to Port 5 (P5). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1, P3, P4 and P5 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Input Port Features

- Configurable input driver
- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- Alternate input for on-chip peripherals
- Analog input for ADC module

3.7 Reset Control

The XC886/888 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC886/888 is first powered up, the status of certain pins (see **Table 23**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9*V_{DDC}. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* $V_{DDC.}$

A typical application example is shown in **Figure 22**. The V_{DDP} capacitor value is 100 nF while the V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the $\overline{\text{RESET}}$ pin should be held low for 500 µs typically. See **Figure 23**.

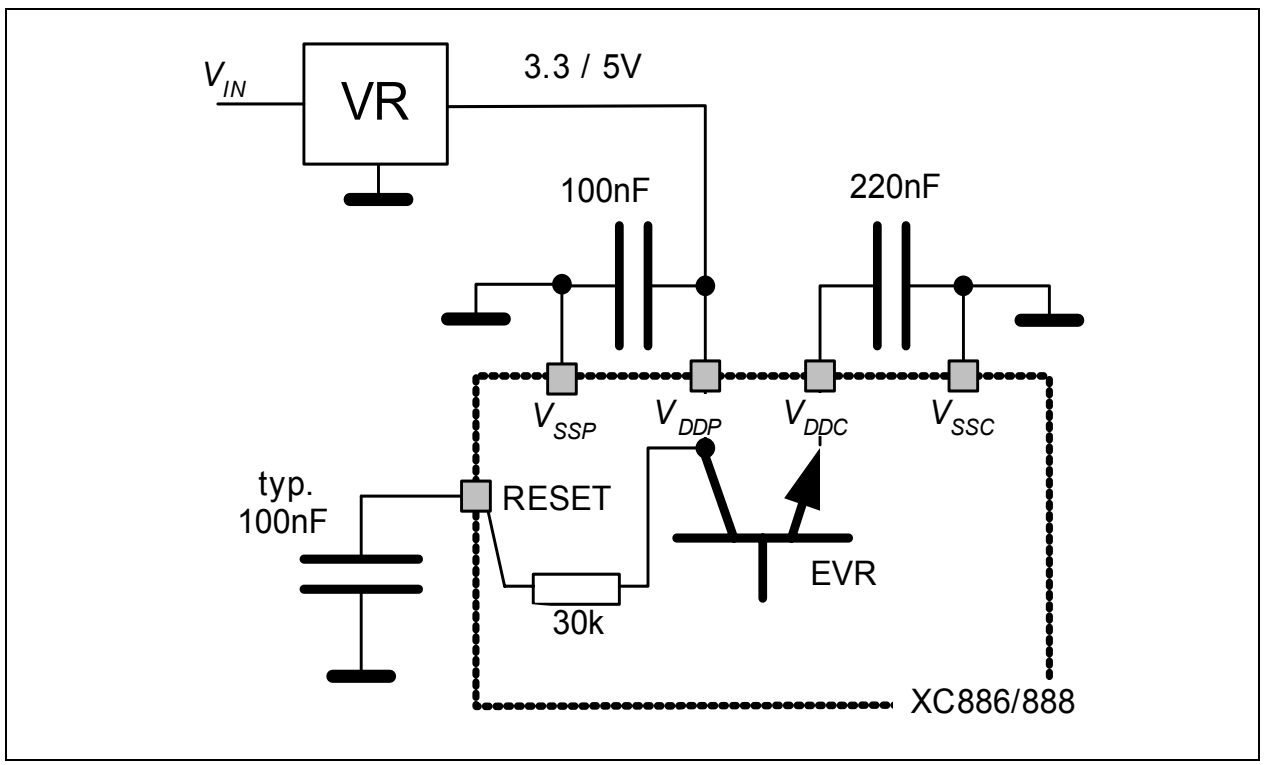


Figure 22 Reset Circuitry

GLOBCTR. A prescaling ratio of 32 can be selected when the maximum performance of the ADC is not required.

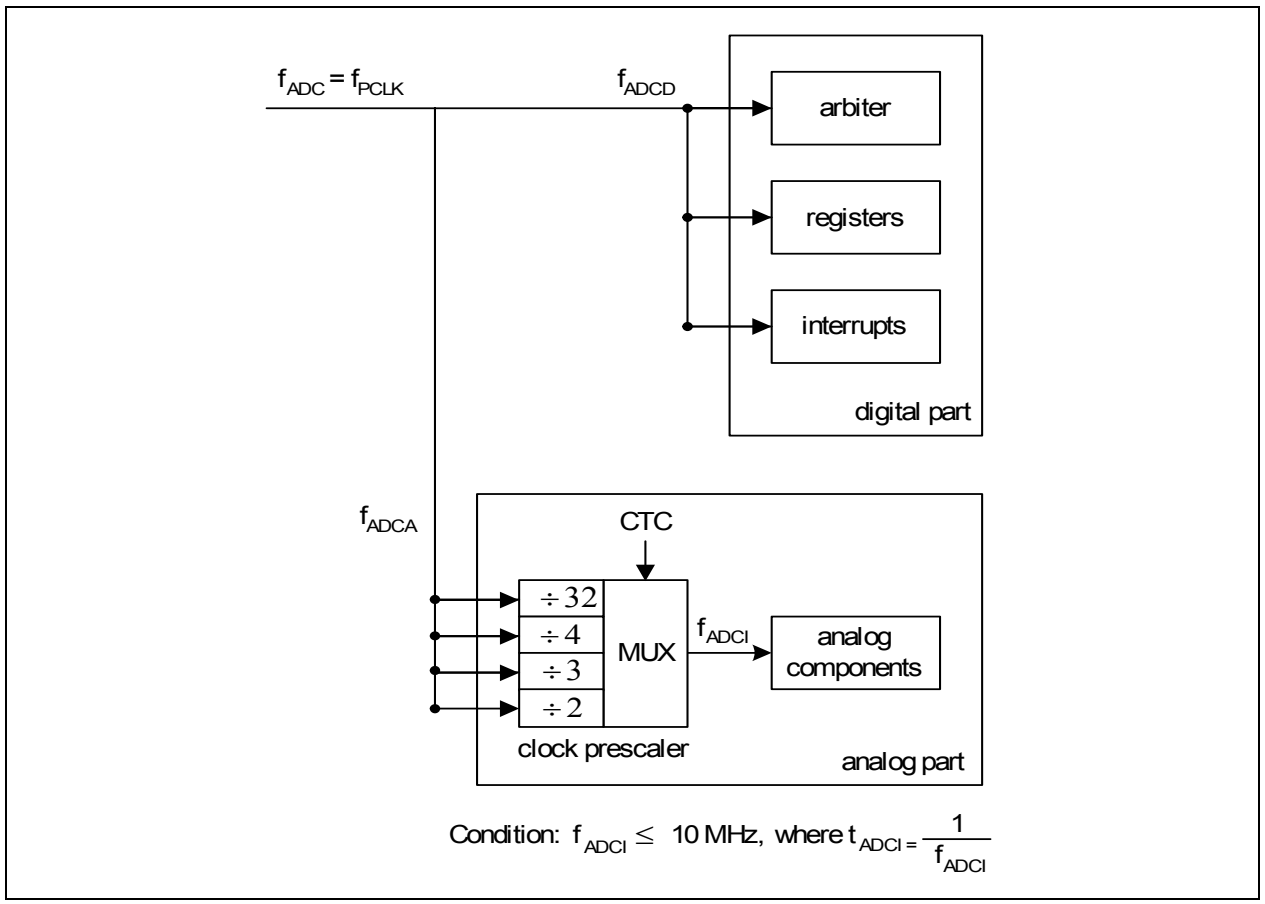


Figure 35 ADC Clocking Scheme

For module clock f_{ADC} = 24 MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 34**.

Table 34 f_{ADCI} Frequency Selection

Module Clock f_{ADC}	CTC	Prescaling Ratio	Analog Clock f_{ADCI}
24 MHz	00_B	÷ 2	12 MHz (N.A)
	01_B	÷ 3	8 MHz
	10_B	÷ 4	6 MHz
	11_B (default)	÷ 32	750 kHz

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 24 MHz. During slow-down mode where f_{ADC} may be reduced to 12 MHz, 6 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz.

Table 36 Chip Identification Number (cont'd)

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
XC886LM-6RFA 3V3	22411522_H	-	-
XC888LM-6RFA 3V3	22411523_H	-	-
XC886CM-8RFA 3V3	22480502_H	-	-
XC888CM-8RFA 3V3	22480503_H	-	-
XC886C-8RFA 3V3	22480542_H	-	-
XC888C-8RFA 3V3	22480543_H	-	-
XC886-8RFA 3V3	22480562_H	-	-
XC888-8RFA 3V3	22480563_H	-	-
XC886CM-6RFA 3V3	22491502_H	-	-
XC888CM-6RFA 3V3	22491503_H	-	-
XC886C-6RFA 3V3	22491542_H	-	-
XC888C-6RFA 3V3	22491543_H	-	-
XC886-6RFA 3V3	22491562_H	-	-
XC888-6RFA 3V3	22491563_H	-	-
XC886CLM-8RFA 5V	22800502_H	-	-
XC888CLM-8RFA 5V	22800503_H	-	-
XC886LM-8RFA 5V	22800522_H	-	-
XC888LM-8RFA 5V	22800523_H	-	-
XC886CLM-6RFA 5V	22811502_H	-	-
XC888CLM-6RFA 5V	22811503_H	-	-
XC886LM-6RFA 5V	22811522_H	-	-
XC888LM-6RFA 5V	22811523_H	-	-
XC886CM-8RFA 5V	22880502_H	-	-
XC888CM-8RFA 5V	22880503_H	-	-
XC886C-8RFA 5V	22880542_H	-	-
XC888C-8RFA 5V	22880543_H	-	-
XC886-8RFA 5V	22880562_H	-	-
XC888-8RFA 5V	22880563_H	-	-
XC886CM-6RFA 5V	22891502_H	-	-

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Table 40 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol		Limit Values			Unit	Test Conditions/ Remarks
			min.	typ .	max.		
Analog reference voltage	V_{AREF}	SR	V_{AGND} + 1	V_{DDP}	V_{DDP} + 0.05	V	[1]
Analog reference ground	V_{AGND}	SR	V_{SS} - 0.05	V_{SS}	V_{AREF} - 1	V	[1]
Analog input voltage range	V_{AIN}	SR	V_{AGND}	–	V_{AREF}	V	
ADC clocks	f_{ADC}		–	24	25.8	MHz	module clock[1]
	f_{ADCI}		–	–	10	MHz	internal analog clock[1] See **Figure 35**
Sample time	t_S	CC	(2 + INPCR0.STC) × t_{ADCI}			µs	[1]
Conversion time	t_C	CC	See **Section 4.2.3.1**			µs	[1]
Total unadjusted error	|TUE|	CC	–	–	1	LSB	8-bit conversion[2]
			–	–	2	LSB	10-bit conversion[2]
Differential Nonlinearity	$\|EA_{DNL}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Integral Nonlinearity	$\|EA_{INL}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Offset	$\|EA_{OFF}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Gain	$\|EA_{GAIN}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Overload current coupling factor for analog inputs	K_{OVA}	CC	–	–	1.0 x 10^{-4}	–	$I_{OV} > 0$[1][3]
			–	–	1.5 x 10^{-3}	–	$I_{OV} < 0$[1][3]

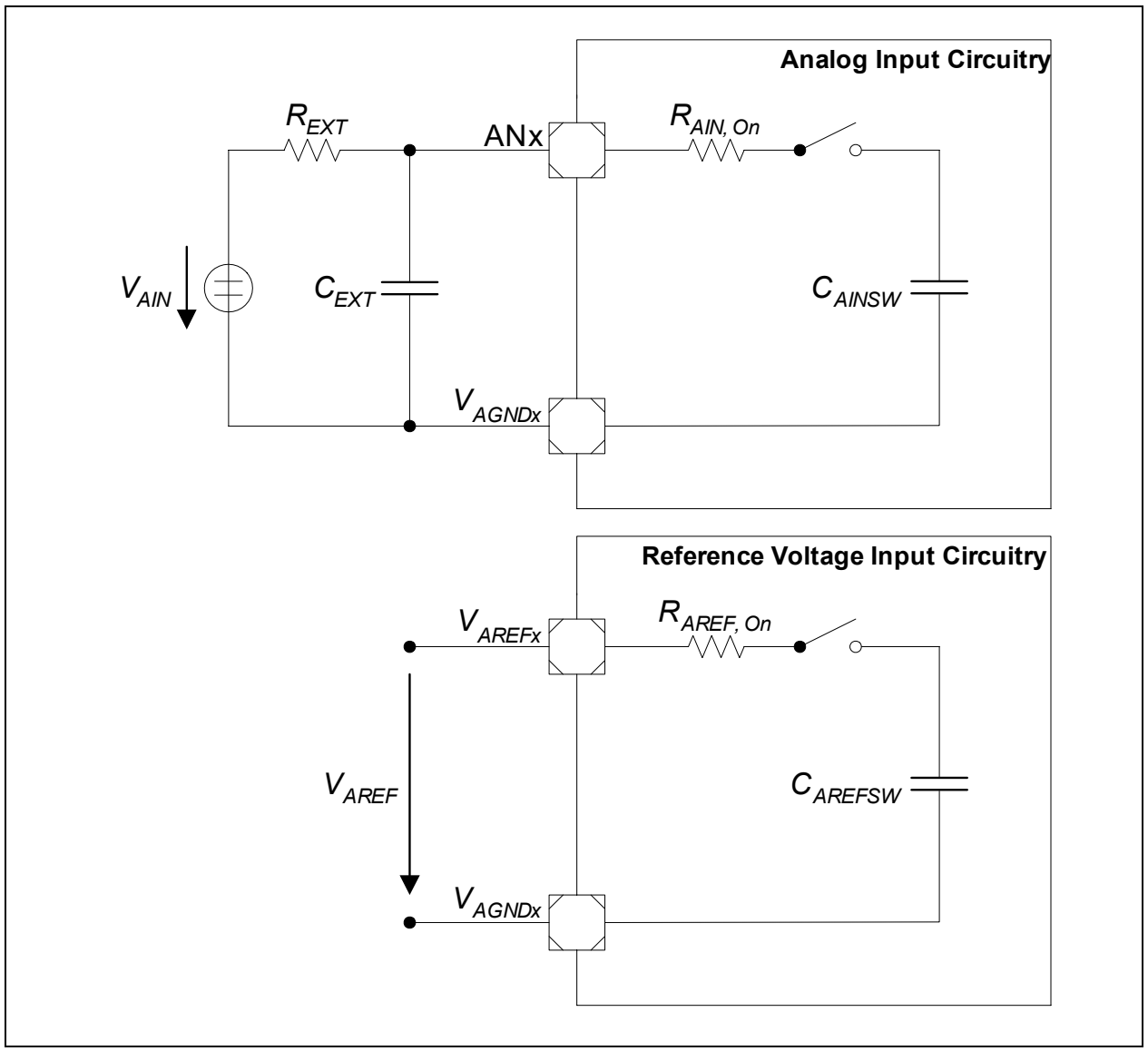


Figure 39 ADC Input Circuits

Table 43 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 3.3V Range					
Active Mode	I_{DDP}	25.6	31.0	mA	Flash Device[3]
		23.4	28.6	mA	ROM Device[3]
Idle Mode	I_{DDP}	19.9	24.7	mA	Flash Device[4]
		17.5	20.7	mA	ROM Device[4]
Active Mode with slow-down enabled	I_{DDP}	13.3	16.2	mA	Flash Device[5]
		11.5	13.7	mA	ROM Device[5]
Idle Mode with slow-down enabled	I_{DDP}	11.1	14.4	mA	Flash Device[6]
		9.3	11.4	mA	ROM Device[6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 3.3 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 3.6 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz(set by on-chip oscillator of 9.6 MHz and NDIV in PLL_CON to 1001_B), $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 8 MHz by setting CLKREL in CMCON to 0110_B, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 8 MHz by setting CLKREL in CMCON to 0110_B,, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4.3.5 External Clock Drive XTAL1

Table 48 shows the parameters that define the external clock supply for XC886/888. These timing parameters are based on the direct XTAL1 drive of clock input signals. They are not applicable if an external crystal or ceramic resonator is considered.

Table 48 External Clock Drive Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Oscillator period	t_{osc}	SR	83.3	250	ns	1)2)
High time	t_1	SR	25	-	ns	2)3)
Low time	t_2	SR	25	-	ns	2)3)
Rise time	t_3	SR	-	20	ns	2)3)
Fall time	t_4	SR	-	20	ns	2)3)

1) The clock input signals with 45-55% duty cycle are used.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

3) The clock input signal must reach the defined levels V_{ILX} and V_{IHX}.

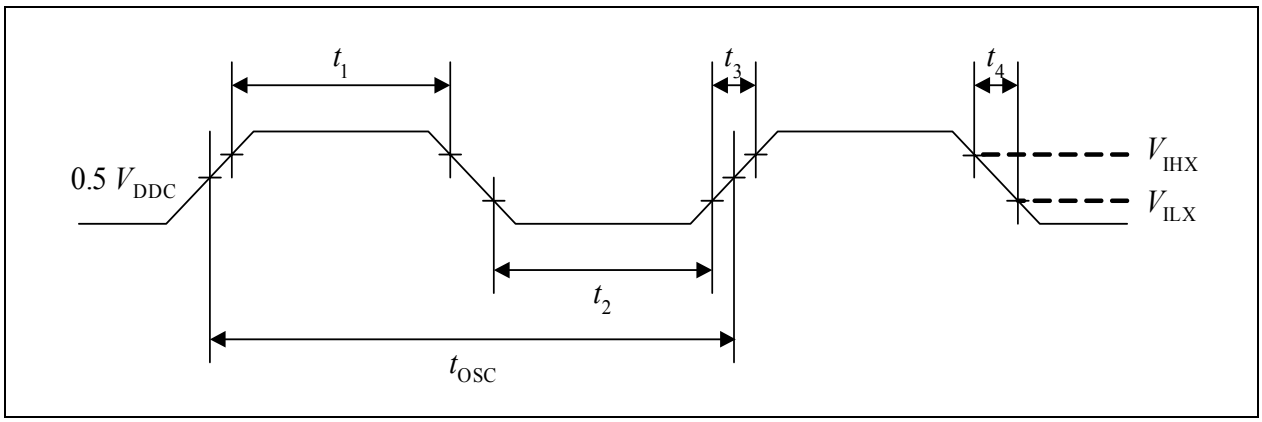
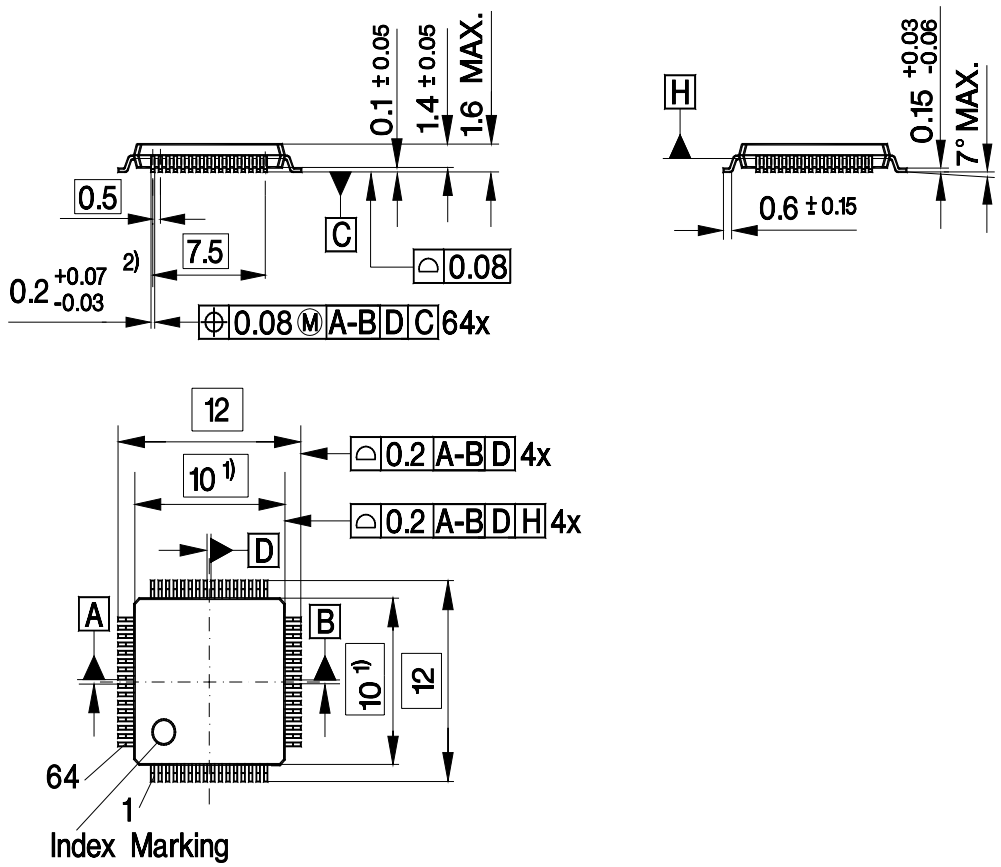


Figure 45 External Clock Drive XTAL1

Figure 49 shows the package outlines of the XC888.



1) Does not include plastic or metal protrusion of 0.25 max. per side
2) Does not include dambar protrusion of 0.08 max. per side

Figure 49 PG-TQFP-64 Package Outline

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